

In re: Hyae-Ryoung Lee
Serial No.: 09/800,138
Filed: March 6, 2001
Page 2

In the Claims:

Please replace Claim 35 with the following like numbered claim:

Q1 35. (Twice Amended) A method of forming a bonding pad for an integrated circuit comprising the steps of:

- forming a dielectric layer on an integrated circuit substrate;
- forming a via hole in the dielectric layer to expose the substrate; and
- forming a conductive pattern in the via hole to form a closed via through the dielectric layer to the substrate to enclose an inner portion of the dielectric layer within the closed via that is separated from an outer portion of the dielectric layer that is outside the closed via.

Please cancel Claims 40-42 without prejudice or disclaimer.